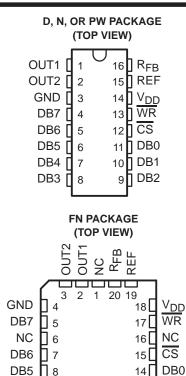
- Easily Interfaced to Microprocessors
- On-Chip Data Latches
- Monotonic Over the Entire A/D Conversion Range
- Segmented High-Order Bits Ensure Low-Glitch Output
- Interchangeable With Analog Devices AD7524, PMI PM-7524, and Micro Power Systems MP7524
- Fast Control Signaling for Digital Signal-Processor Applications Including Interface With TMS320
- CMOS Technology

KEY PERFORMANCE SPECIFICATIONS						
Resolution	8 Bits					
Linearity error	1/2 LSB Max					
Power dissipation at V <sub>DD</sub> = 5 V	5 mW Max					
Setting time	100 ns Max					
Propagation delay time	80 ns Max					

#### description

The TLC7524C, TLC7524E, and TLC7524I are CMOS, 8-bit, digital-to-analog converters (DACs) designed for easy interface to most popular microprocessors.



NC-No internal connection

)B3

DB2

98

The devices are 8-bit, multiplying DACs with input latches and load cycles similar to the write cycles of a random access memory. Segmenting the high-order bits minimizes glitches during changes in the most significant bits, which produce the highest glitch impulse. The devices provide accuracy to 1/2 LSB without the need for thin-film resistors or laser trimming, while dissipating less than 5 mW typically.

Featuring operation from a 5-V to 15-V single supply, these devices interface easily to most microprocessor buses or output ports. The 2- or 4-quadrant multiplying makes these devices an ideal choice for many microprocessor-controlled gain-setting and signal-control applications.

The TLC7524C is characterized for operation from  $0^{\circ}$ C to  $70^{\circ}$ C. The TLC7524I is characterized for operation from  $-25^{\circ}$ C to  $85^{\circ}$ C. The TLC7524E is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

#### **AVAILABLE OPTIONS**

		PACKAGE		
TA	SMALL OUTLINE PLASTIC DIP (D)	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)	SMALL OUTLINE (PW)
0°C to 70°C	TLC7524CD	TLC7524CFN	TLC7524CN	TLC7524CPW
-25°C to 85°C	TLC7524ID	TLC7524IFN	TLC7524IN	TLC7524IPW
-40°C to 85°C	TLC7524ED	TLC7524EFN	TLC7524EN	_

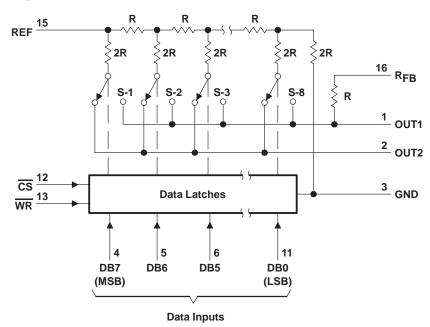


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### functional block diagram



Terminal numbers shown are for the D or N package.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>DD</sub> –0.3 V to 16.5 V
Digital input voltage range, V <sub>I</sub> 0.3 V to V <sub>DD</sub> + 0.3 V
Reference voltage, V <sub>ref</sub> ±25 V
Peak digital input current, I <sub>1</sub>
Operating free-air temperature range, T <sub>A</sub> : TLC7524C
TLC7524I –25°C to 85°C
TLC7524E –40°C to 85°C
Storage temperature range, T <sub>stq</sub> –65°C to 150°C
Case temperature for 10 seconds, T <sub>C</sub> : FN package
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds: D. N. or PW package



# TLC7524C, TLC7524E, TLC7524I 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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### recommended operating conditions

			V <sub>DD</sub> = 5 V		V <sub>DD</sub> = 15 V			UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>DD</sub>			4.75	5	5.25	14.5	15	15.5	V
Reference voltage, V <sub>ref</sub>				±10			±10		V
High-level input voltage, VIH			2.4			13.5			V
Low-level input voltage, V <sub>IL</sub>	Low-level input voltage, V <sub>I</sub> L				0.8			1.5	V
CS setup time, t <sub>SU(CS)</sub>	CS setup time, t <sub>SU(CS)</sub>					40			ns
CS hold time, th(CS)			0			0			ns
Data bus input setup time, t <sub>Su(D)</sub>	Data bus input setup time, t <sub>Su(D)</sub>					25			ns
Data bus input hold time, th(D)			10			10			ns
Pulse duration, WR low, t <sub>w(WR)</sub>		40			40			ns	
	TLC7524C	·	0		70	0		70	
Operating free-air temperature, TA	TLC7524I	·	-25		85	-25		85	°C
	TLC7524E		-40		85	-40		85	

## electrical characteristics over recommended operating free-air temperature range, $V_{ref}$ = $\pm 10$ V, OUT1 and OUT2 at GND (unless otherwise noted)

	PARAMETER		TEST CONDITIONS		V <sub>DD</sub> = 5 V		۷۲	D = 15	٧	UNIT
			TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNII
lн	High-level input curre	nt	$V_I = V_{DD}$			10			10	μΑ
Ι <sub>Ι</sub> L	Low-level input currer	nt	V <sub>I</sub> = 0			-10			-10	μΑ
	Output leakage current	OUT1	DB0-DB7 at 0 V, $\overline{WR}$ , $\overline{CS}$ at 0 V, $\overline{Vref} = \pm 10 \text{ V}$	±400				±200		
llkg		OUT2	DB0-DB7 at $V_{DD}$ , $\overline{WR}$ , $\overline{CS}$ at 0 V, $V_{ref} = \pm 10 \text{ V}$			±400			±200	nA
	Cupply ourrent	Quiescent	DB0-DB7 at V <sub>IH</sub> min or V <sub>IL</sub> max			1			2	mA
IDD	Supply current	Standby	DB0-DB7 at 0 V or V <sub>DD</sub>			500			500	μΑ
ksvs	ksvs Supply voltage sensitivity, Δgain/ΔVDD		$\Delta V_{DD} = \pm 10\%$		0.01	0.16		0.005	0.04	%FSR/%
Ci	Ci Input capacitance, DB0-DB7, WR, CS		V <sub>I</sub> = 0			5			5	pF
		OUT1	DB0-DB7 at 0 V, WR, CS at 0 V			30			30	
	Output capacitance	OUT2	DB0-DB7 at 0 V, WR, CS at 0 V			120			120	
Co		OUT1	DD0 DD7 -111	120			120		pF	
		OUT2	DB0–DB7 at $V_{DD}$ , $\overline{WR}$ , $\overline{CS}$ at 0 $V$			30			30	
	Reference input impedance (REF to GND)			5		20	5		20	kΩ

# TLC7524C, TLC7524E, TLC7524I 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

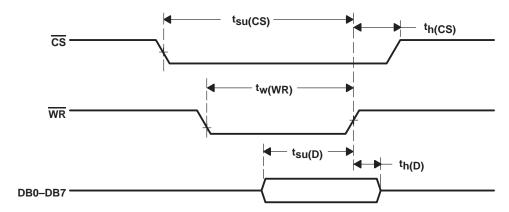
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## operating characteristics over recommended operating free-air temperature range, $V_{ref}$ = $\pm 10$ V, OUT1 and OUT2 at GND (unless otherwise noted)

DADAMETED TEST CONDITIONS		V <sub>DD</sub> = 5 V			V <sub>DD</sub> = 15 V			UNIT
PARAMETER	PARAMETER TEST CONDITIONS		TYP	MAX	MIN	TYP	MAX	UNII
Linearity error				±0.5			±0.5	LSB
Gain error	See Note 1			±2.5			±2.5	LSB
Settling time (to 1/2 LSB)	See Note 2			100			100	ns
Propagation delay from digital input to 90% of final analog output current	See Note 2			80			80	ns
Feedthrough at OUT1 or OUT2	$\frac{\text{Vref} = \pm 10 \text{ V} (100\text{-kHz sinewave})}{\text{WR and } \overline{\text{CS}} \text{ at 0 V, DB0-DB7 at 0 V}}$			0.5			0.5	%FSR
Temperature coefficient of gain	$T_A = 25^{\circ}C$ to MAX	±0.004 ±0.001		%FSR/°C				

Gain error is measured using the internal feedback resistor. Nominal full-scale range (FSR) = V<sub>ref</sub> - 1 LSB.
 OUT1 load = 100 Ω, C<sub>ext</sub> = 13 pF, WR at 0 V, CS at 0 V, DB0 - DB7 at 0 V to V<sub>DD</sub> or V<sub>DD</sub> to 0 V.

#### operating sequence



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#### PRINCIPLES OF OPERATION

#### voltage-mode operation

It is possible to operate the current-multiplying DAC in these devices in a voltage mode. In the voltage mode, a fixed voltage is placed on the current output terminal. The analog output voltage is then available at the reference voltage terminal. Figure 1 is an example of a current-multiplying DAC, which is operated in voltage mode.

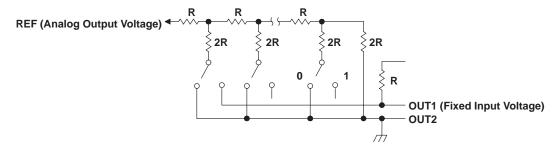


Figure 1. Voltage Mode Operation

The relationship between the fixed-input voltage and the analog-output voltage is given by the following equation:

$$V_0 = V_1 (D/256)$$

where

V<sub>O</sub> = analog output voltage

V<sub>I</sub> = fixed input voltage

D = digital input code converted to decimal

In voltage-mode operation, these devices meet the following specification:

PARAMETER	TEST CONDITIONS	MIN MAX	UNIT
Linearity error at REF	$V_{DD} = 5 \text{ V}$ , OUT1 = 2.5 V, OUT2 at GND, $T_A = 25^{\circ}\text{C}$	1	LSB

The TLC7524C, TLC7524E, and TLC7524I are 8-bit multiplying DACs consisting of an inverted R-2R ladder, analog switches, and data input latches. Binary-weighted currents are switched between the OUT1 and OUT2 bus lines, thus maintaining a constant current in each ladder leg independent of the switch state. The high-order bits are decoded. These decoded bits, through a modification in the R-2R ladder, control three equally-weighted current sources. Most applications only require the addition of an external operational amplifier and a voltage reference.

The equivalent circuit for all digital inputs low is seen in Figure 2. With all digital inputs low, the entire reference current, I<sub>ref</sub>, is switched to OUT2. The current source I/256 represents the constant current flowing through the termination resistor of the R-2R ladder, while the current source I<sub>Ikg</sub> represents leakage currents to the substrate. The capacitances appearing at OUT1 and OUT2 are dependent upon the digital input code. With all digital inputs high, the off-state switch capacitance (30 pF maximum) appears at OUT2 and the on-state switch capacitance (120 pF maximum) appears at OUT1. With all digital inputs low, the situation is reversed as shown in Figure 2. Analysis of the circuit for all digital inputs high is similar to Figure 2; however, in this case, I<sub>ref</sub> would be switched to OUT1.

The DAC on these devices interfaces to a microprocessor through the data bus and the  $\overline{\text{CS}}$  and  $\overline{\text{WR}}$  control signals. When  $\overline{\text{CS}}$  and  $\overline{\text{WR}}$  are both low, analog output on these devices responds to the data activity on the DB0–DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the  $\overline{\text{CS}}$  signal or  $\overline{\text{WR}}$  signal goes high, the data on the DB0–DB7 inputs are latched until the  $\overline{\text{CS}}$  and  $\overline{\text{WR}}$  signals go low again. When  $\overline{\text{CS}}$  is high, the data inputs are disabled regardless of the state of the  $\overline{\text{WR}}$  signal.

These devices are capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant or 4-quadrant multiplication are shown in Figure 3 and Figure 4. Table 1 and Table 2 summarize input coding for unipolar and bipolar operation respectively.

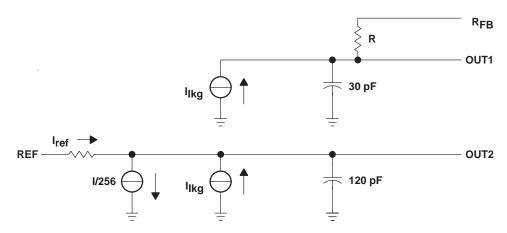
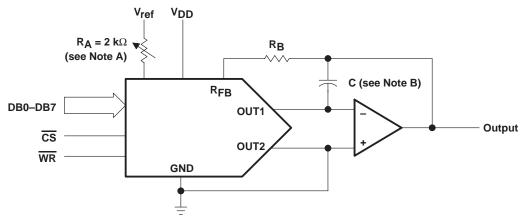
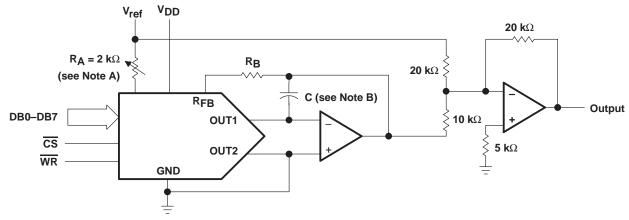


Figure 2. TLC7524 Equivalent Circuit With All Digital Inputs Low



- NOTES: A.  $\mathsf{R}_A$  and  $\mathsf{R}_B$  used only if gain adjustment is required.
  - B. C phase compensation (10-15 pF) is required when using high-speed amplifiers to prevent ringing or oscillation.

Figure 3. Unipolar Operation (2-Quadrant Multiplication)



- NOTES: A. RA and RB used only if gain adjustment is required.
  - B. C phase compensation (10-15 pF) is required when using high-speed amplifiers to prevent ringing or oscillation.

Figure 4. Bipolar Operation (4-Quadrant Operation)

Table 1. Unipolar Binary Code

1			<u> </u>
	DIGITAL		
	(see N	ote 3)	ANALOG OUTPUT
	MSB	LSB	
	1111	1111	-V <sub>ref</sub> (255/256)
	1000	0001	-V <sub>ref</sub> (129/256)
	1000	0000	$-V_{ref}$ (128/256) = $-V_{ref}$ /2
	0111	1111	-V <sub>ref</sub> (127/256)
	00000	0001	-V <sub>ref</sub> (1/256)
	0000	0000	0

NOTE 3: LSB =  $1/256 (V_{ref})$ 

Table 2. Bipolar (Offset Binary) Code

DIGITAL (see No		ANALOG OUTPUT
MSB	LSB	1
1111	1111	V <sub>ref</sub> (127/128)
1000	0001	V <sub>ref</sub> (1/128)
1000	0000	0
0111	1111	-V <sub>ref</sub> (1/128)
00000	0001	-V <sub>ref</sub> (127/128)
0000	0000	-V <sub>ref</sub>

NOTE 4: LSB =  $1/128 \text{ (V}_{ref})$ 



### microprocessor interfaces

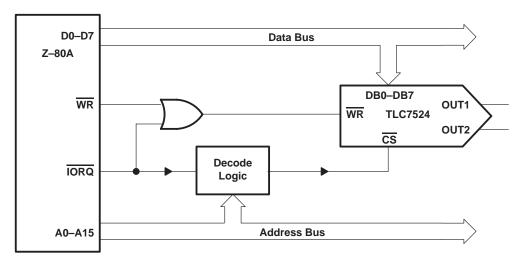


Figure 5. TLC7524 – Z-80A Interface

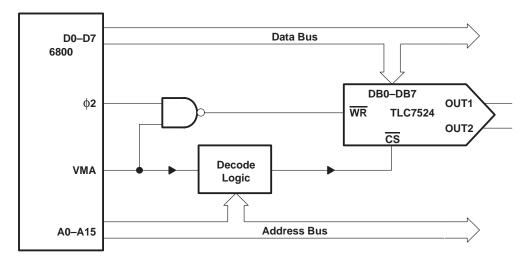


Figure 6. TLC7524 - 6800 Interface

## microprocessor interfaces (continued)

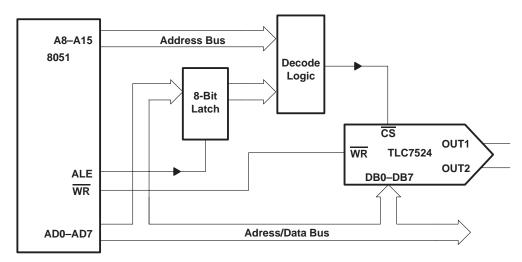


Figure 7. TLC7524 - 8051 Interface

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